



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130425002

**Transfer of select devices in the Vertical Diode-ULC process node to CFAB Facility
Change Notification / Sample Request**

Date: 4/30/2013
To: MOUSER PCN

Dear Customer:

In January, 2012, TI announced plans to close two older 6-inch manufacturing facilities in Hiji, Japan and Houston, Texas. This product change announcement is to support transfer of products in the Vertical Diode-Ultra Low Capacitance process node from these wafer fabs to an alternate site. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days to ensure you can complete your evaluation and product transfer to the new site can be completed prior to the fab closure.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659










20130425002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPD4E1U06DBVR	null
TPD4E1U06DCKR	null
TPD1E05U06DPYT	null
TPD4E05U06DQAR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130425002		PCN Date:	04/30/2013							
Title:	Transfer of select devices in the Vertical Diode-Ultra Low Capacitance process node to CFAB Facility										
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037		Dept: Quality Services						
*Proposed 1st Ship Date:	08/2013		Estimated Sample Availability:	Date provided upon Samples Request							
Change Type:											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials						
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification						
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process						
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process						
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/>	Wafer Fab Process						
PCN Details											
Description of Change:											
<p>This change notification is to announce the transfer of select devices in the Vertical Diode –Ultra Low Capacitance (ULC) process node from HIJI to the CFAB facility. This will also include a wafer diameter change from 6" to 8".</p> <table border="1"> <thead> <tr> <th>Current</th> <th>New</th> </tr> </thead> <tbody> <tr> <td>Site, process, wafer dia.</td> <td>Site, process, wafer dia.</td> </tr> <tr> <td>HIJI/ VD-ULC, 150mm</td> <td>CFAB/ VD-ULC, 200mm</td> </tr> </tbody> </table> <p>*The 1st ship date is based on current qual plan schedule.</p>						Current	New	Site, process, wafer dia.	Site, process, wafer dia.	HIJI/ VD-ULC, 150mm	CFAB/ VD-ULC, 200mm
Current	New										
Site, process, wafer dia.	Site, process, wafer dia.										
HIJI/ VD-ULC, 150mm	CFAB/ VD-ULC, 200mm										
Reason for Change:											
Continuity of Supply. HIJI site shutdown.											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Changes to product identification resulting from this PCN:											
Current											
Chip Site	Chip site code (20L)	Chip country code (21L)									
HIJI	HIJ	JPN									
New											
Chip Site	Chip site code (20L)	Chip country code (21L)									
CFAB	CU3	CHN									
Sample product shipping label (not actual product label)											
<table border="1"> <tr> <td>  TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2d: MSL '2 / 260C/1 YEAR MSL 1 / 235C/UNLIM OPT: 39 ITEM: LBL: 5A (L)T0:1750 </td> <td>  </td> <td>  </td> <td> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21) CCO:USA (22L) AS0:MLA (23L) AG0:MYS </td> </tr> </table>						 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2d: MSL '2 / 260C/1 YEAR MSL 1 / 235C/UNLIM OPT: 39 ITEM: LBL: 5A (L)T0:1750			(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21) CCO:USA (22L) AS0:MLA (23L) AG0:MYS		
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2d: MSL '2 / 260C/1 YEAR MSL 1 / 235C/UNLIM OPT: 39 ITEM: LBL: 5A (L)T0:1750			(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21) CCO:USA (22L) AS0:MLA (23L) AG0:MYS								

Product Affected:				
TPD1E02B06DPLR	TPD1E05U06DPYT	TPD4E1B06DCKR	TPD6E05U06RVZR	
TPD1E02B06DPLT	TPD2E2U06DRLR-P	TPD4E1U06DBVR		
TPD1E05U06DPYR	TPD4E05U06DQAR	TPD4E1U06DCKR		

Qualification Plan:					
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.					
Qualification Schedule:		Start:	06/2013	End: 08/2013	
Qual Vehicle: TPD4E1U06DCKR					
Wafer Fab Site:		CFAB	Metallization:	AlCuTiW	
Wafer Fab Process:		VD-ULC	Wafer Diameter:	200mm	
Qualification: <input checked="" type="checkbox"/> Plan <input type="checkbox"/> Test Results					
Reliability Test		Conditions	Sample Size/Fails		
			Lot#1	Lot#2	Lot#3
Preconditioning		-	231/0	231/0	231/0
HTOL High Temp Op Life		150C (300 Hrs)	77/0	-	-
Electrical Characterization		-	30/0	30/0	30/0
**High Temp. Storage Bake		170C (420 Hrs)	77/0	77/0	77/0
**Unbiased HAST		130C/85%RH (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C		-65C/+150C (500 Cycles)	77/0	77/0	77/0
ESD CDM		500V	3/0	3/0	3/0
ESD HBM		1000V	3/0	3/0	3/0
Manufacturability (Assembly)		(per mfg. Site specification)	1/0	1/0	1/0
**Preconditioning: Level 1-260C					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com